# **Dual Non-Inverting Schmitt-Trigger Buffer**

The NLU2G17 MiniGate<sup>™</sup> is an advanced high-speed CMOS dual non-inverting Schmitt-trigger buffer in ultra-small footprint.

The NLU2G17 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

The NLU2G17 can be used to enhance noise immunity or to square up slowly changing waveforms.

### **Features**

- High Speed:  $t_{PD} = 4.0 \text{ ns (Typ)} @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \mu A$  (Max) at  $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

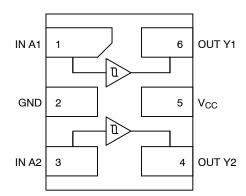


Figure 1. Pinout (Top View)

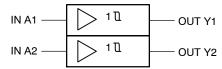


Figure 2. Logic Symbol



# ON Semiconductor®

http://onsemi.com

# MARKING DIAGRAMS



UDFN6 MU SUFFIX CASE 517AA





ULLGA6 1.0 x 1.0 CASE 613AD





ULLGA6 1.2 x 1.0 CASE 613AE





ULLGA6 1.45 x 1.0 CASE 613AF



A = Device Marking M = Date Code

# **PIN ASSIGNMENT**

1	IN A1			
2	GND			
3	IN A2			
4	OUT Y2			
5	V <sub>CC</sub>			
6	OUT Y1			

# **FUNCTION TABLE**

A	Y
L H	L H

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

### **MAXIMUM RATINGS**

Symbol	Paramete	Parameter			
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V		
V <sub>IN</sub>	DC Input Voltage		-0.5 to +7.0	V	
V <sub>OUT</sub>	DC Output Voltage		-0.5 to +7.0	V	
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < GND	-20	mA	
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < GND	±20	mA	
Ιο	DC Output Source/Sink Current	±12.5	mA		
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±25	mA		
I <sub>GND</sub>	DC Ground Current per Ground Pin	±25	mA		
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C		
TL	Lead Temperature, 1 mm from Case for 10 Sec	conds	260	°C	
TJ	Junction Temperature Under Bias	150	°C		
MSL	Moisture Sensitivity	Level 1			
F <sub>R</sub>	Flammability Rating Oxygen	UL 94 V-0 @ 0.125 in			
I <sub>LATCHUP</sub>	Latchup Performance Above V <sub>CC</sub> and Below G	iND at 125°C (Note 2)	±500	mA	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
   Tested to EIA / JESD78.

# RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage	1.65	5.5	V
V <sub>IN</sub>	Digital Input Voltage	0	5.5	V
V <sub>OUT</sub>	Output Voltage	0	5.5	V
T <sub>A</sub>	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}  $ $ V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V} $	0 0	No Limit No Limit	ns/V

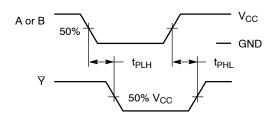
# DC ELECTRICAL CHARACTERISTICS

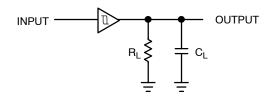
			V <sub>CC</sub>		T <sub>A</sub> = 25 °C		T <sub>A</sub> = 25 °C		<b>T</b> <sub>A</sub> = -	+85°C		55°C to 5°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit		
V <sub>T+</sub>	Positive Threshold Voltage		3.0 4.5 5.5	1.85 2.86 3.50	2.0 3.0 3.6	2.2 3.15 3.85		2.2 3.15 3.85		2.2 3.15 3.85	V		
V <sub>T-</sub>	Negative Threshold Voltage		3.0 4.5 5.5	0.9 1.35 1.65	1.5 2.3 2.9	1.65 2.46 3.05	0.9 1.35 1.65		0.9 1.35 1.65		V		
V <sub>H</sub>	Hysteresis Voltage		3.0 4.5 5.5	0.30 0.40 0.50	0.57 0.67 0.74	1.20 1.40 1.60	0.30 0.40 0.50	1.20 1.40 1.60	0.30 0.40 0.50	1.20 1.40 1.60	V		
V <sub>OH</sub>	Minimum High-Level Output	$V_{IN} \ge V_{T+MAX}$ $I_{OH} = -50 \mu A$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V		
	Voltage	$V_{IN} \ge V_{T+MAX}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66				
V <sub>OL</sub>	Maximum Low-Level Output Voltage	$V_{IN} \le V_{T-MIN}$ $I_{OL} = 50 \mu A$	2.0 3.0 4.5		0 0 0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	٧		
	vollage	$\begin{aligned} &V_{IN} \leq V_{T-MIN} \\ &I_{OL} = 4 \text{ mA} \\ &I_{OL} = 8 \text{ mA} \end{aligned}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52			
I <sub>IN</sub>	Input Leakage Current	0 ≤ V <sub>IN</sub> ≤ 5.5 V	0 to 5.5			±0.1		±1.0		±1.0	μΑ		
I <sub>CC</sub>	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		10		40	μΑ		

# AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$ )

		V <sub>CC</sub>	Test		T <sub>A</sub> = 25 °	С	T <sub>A</sub> =	+85°C		55°C to 5°C	
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation Delay,	3.0 to	C <sub>L</sub> = 15 pF		7.0	12.8	1.0	15	1.0	17	ns
t <sub>PHL</sub>	Input A to Output ₹	3.6	C <sub>L</sub> = 50 pF		8.5	16.3	1.0	18.5	1.0	20.5	
		4.5 to	C <sub>L</sub> = 15 pF		4.0	8.6	1.0	10	1.0	11.5	
		5.5	C <sub>L</sub> = 50 pF		5.5	10.6	1.0	12	1.0	13.5	
C <sub>IN</sub>	Input Capacitance				5.0	10		10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 3)	5.0			7.0						pF

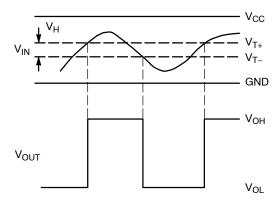
<sup>3.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.



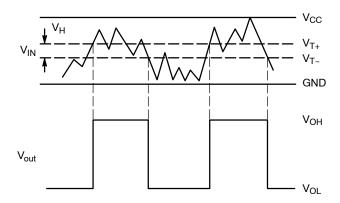


A 1-MHz square input wave is recommended for propagation delay tests.

Figure 3. Switching Waveforms







(a) A Schmitt-Trigger Squares Up Inputs With Slow Rise and Fall Times

(b) A Schmitt-Trigger Offers Maximum Noise Immunity

Figure 5. Typical Schmitt-Trigger Applications

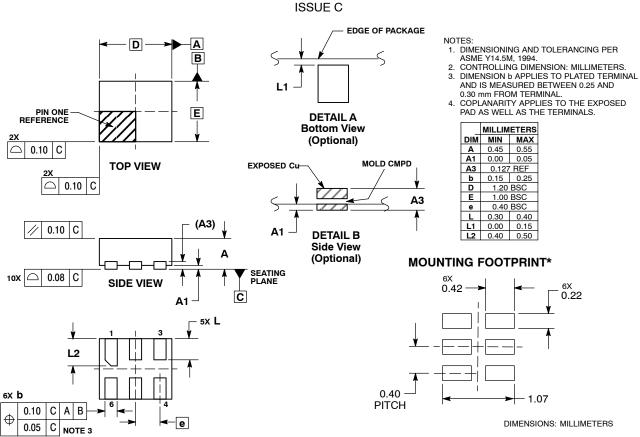
# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NLU2G17MUTCG	UDFN6 (Pb-Free)	3000 / Tape & Reel
NLU2G17AMX1TCG	ULLGA6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLU2G17BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLU2G17CMX1TCG	ULLGA6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **PACKAGE DIMENSIONS**

# UDFN6, 1.2x1.0, 0.4P CASE 517AA-01

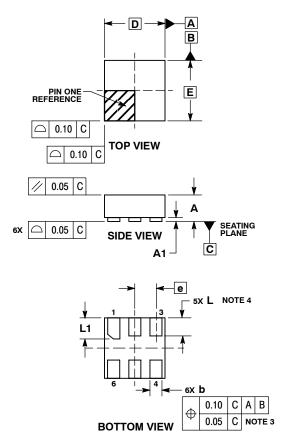


**BOTTOM VIEW** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **PACKAGE DIMENSIONS**

ULLGA6 1.0x1.0, 0.35P CASE 613AD-01 ISSUE A



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

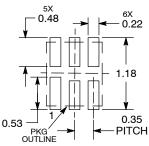
  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

  4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALL OWED.
- PACKAGE IS ALLOWED.

_	MILLIMETERS					
DIM	MIN	MAX				
Α		0.40				
A1	0.00	0.05				
b	0.12	0.22				
D	1.00 BSC					
Е	1.00 BSC					
е	0.35 BSC					
L	0.25	0.35				
11	0.30	0.40				

# **MOUNTING FOOTPRINT SOLDERMASK DEFINED\***

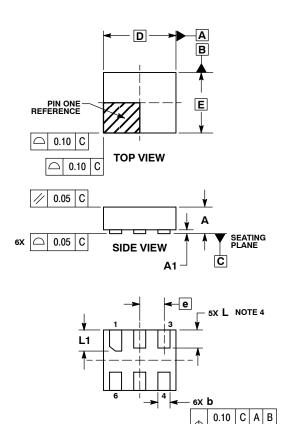


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **PACKAGE DIMENSIONS**

ULLGA6 1.2x1.0, 0.4P CASE 613AE-01 ISSUE A



**BOTTOM VIEW** 

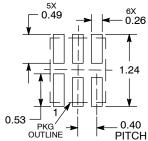
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0.05 C NOTE 3

- NOTES:
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  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
  4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	<b>MILLIMETERS</b>						
DIM	MIN	MAX					
Α		0.40					
<b>A</b> 1	0.00	0.05					
b	0.15	0.25					
D	1.20 BSC						
Е	1.00 BSC						
е	0.40 BSC						
L	0.25	0.35					
L1	0.35	0.45					

# MOUNTING FOOTPRINT **SOLDERMASK DEFINED\***

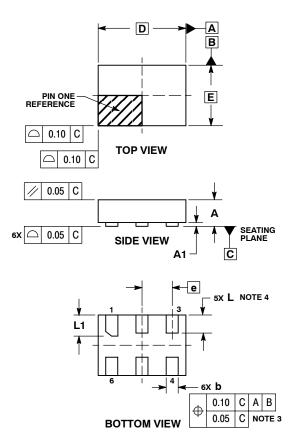


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# PACKAGE DIMENSIONS

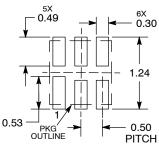
ULLGA6 1.45x1.0, 0.5P CASE 613AF-01 **ISSUE A** 



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  0.30 mm FROM THE TERMINAL TIP.
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	MILLIMETERS						
DIM	MIN	MAX					
Α		0.40					
A1	0.00	0.05					
b	0.15	0.25					
D	1.45 BSC						
Е	1.00 BSC						
е	0.50 BSC						
L	0.25	0.35					
L1	0.30	0.40					

### MOUNTING FOOTPRINT SOLDERMASK DEFINED\*



DIMENSIONS: MILLIMETERS

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